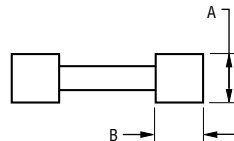
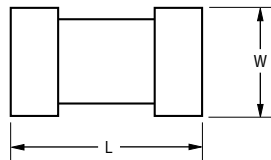


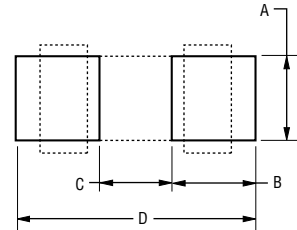
ChipGuard® MLC Series - ESD Protectors

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Product Dimensions



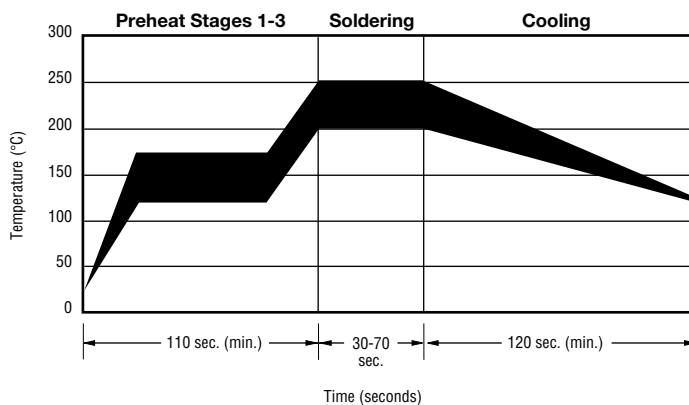
DIMENSIONS: $\frac{\text{MM}}{(\text{INCHES})}$



Dimension	CG0402 Series	CG0603 Series
L	$\frac{1.00 \pm 0.15}{(0.04 \pm 0.006)}$	$\frac{1.60 \pm 0.20}{(0.064 \pm 0.008)}$
W	$\frac{0.50 \pm 0.10}{(0.02 \pm 0.004)}$	$\frac{0.80 \pm 0.20}{(0.032 \pm 0.008)}$
A	$\frac{0.36 \pm 0.05}{(0.014 \pm 0.002)}$	$\frac{0.45 \pm 0.10}{(0.018 \pm 0.004)}$
B	$\frac{0.25 \pm 0.15}{(0.01 \pm 0.006)}$	$\frac{0.30 \pm 0.20}{(0.012 \pm 0.008)}$

Dim.	CG0402 Series	CG0603 Series
A	$\frac{0.51}{(0.020)}$	$\frac{0.76}{(0.030)}$
B	$\frac{0.61}{(0.024)}$	$\frac{1.02}{(0.040)}$
C	$\frac{0.51}{(0.020)}$	$\frac{0.50}{(0.020)}$
D	$\frac{1.70}{(0.067)}$	$\frac{2.54}{(0.100)}$

Solder Reflow Recommendations



A	Stage 1 Preheat	Ambient to Preheating Temperature	30 s to 60 s
B	Stage 2 Preheat	140 °C to 160 °C	60 s to 120 s
C	Stage 3 Preheat	Preheat to 200 °C	20 s to 40 s
D	Main Heating	200 °C 210 °C 220 °C 230 °C 240 °C 250 °C to 255 °C	60 s to 70 s 55 s to 65 s 50 s to 60 s 40 s to 50 s 30 s to 40 s 5 s
E	Cooling	200 °C to 100 °C	1 °C/s to 4 °C/s

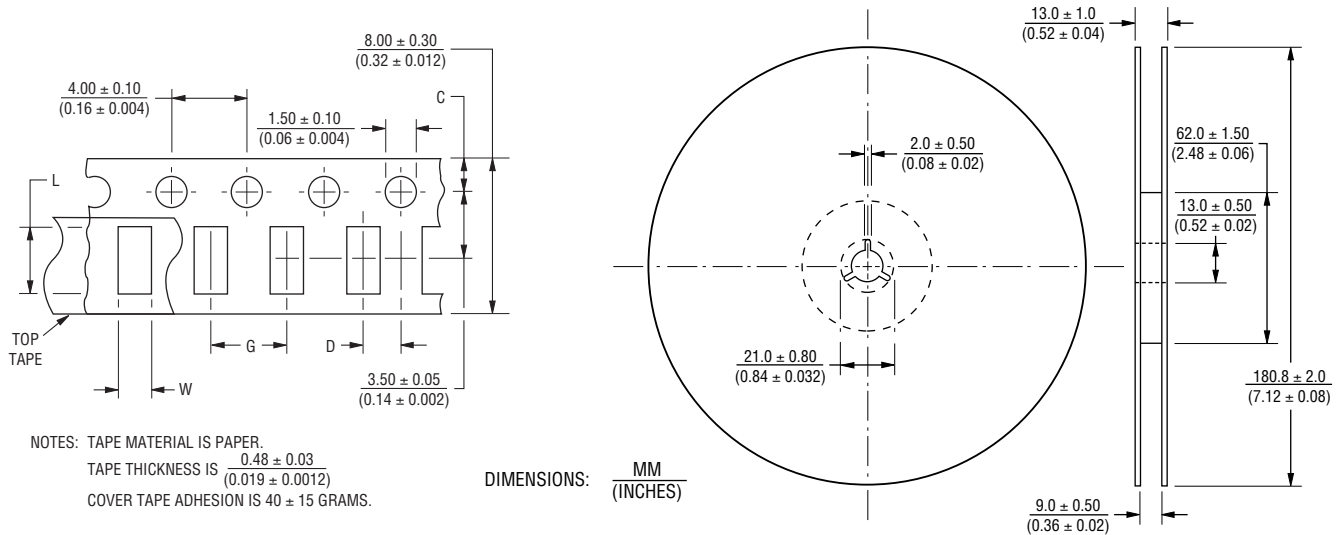
- This product can be damaged by rapid heating, cooling or localized heating.
- Heat shocks should be avoided. Preheating and gradual cooling recommended.
- Excessive solder can damage the device. Print solder thickness of 150 to 200 um recommended.
- Solder gun tip temperature should be kept below 280 °C and should not touch the device directly. Contact should be less than 3 seconds. A solder gun under 30 watts is recommended.

Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.

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Packaging Dimensions



Dimension	CG0402 Series	CG0603 Series
C	1.75 ± 0.05 (0.04 ± 0.002)	1.75 ± 0.10 (0.04 ± 0.004)
D	2.00 ± 0.02 (0.08 ± 0.0008)	2.00 ± 0.05 (0.08 ± 0.002)
L	1.12 ± 0.03 (0.045 ± 0.0012)	1.80 ± 0.20 (0.072 ± 0.008)
W	0.62 ± 0.03 (0.025 ± 0.0012)	0.90 ± 0.20 (0.036 ± 0.008)
G	2.0 ± 0.05 (0.08 ± 0.002)	4.0 ± 0.05 (0.16 ± 0.002)

How to Order

CG 0n0n MLC - n.n x x x x

ChipGuard®
Product Designator
Package Option
0402 = 0402 Package
0603 = 0603 Package
Multilayer Series Designator
Operating Voltage**
3.3 = 3.3 V
05 = 5 V
12 = 12 V
24 = 24 V
Low Leakage Current Option
L = Low Leakage Current
Blank = Standard Product
Tape & Reel Packaging
E = 5,000 pcs. per reel (0603 Package)
G = 10,000 pcs. per reel (0402 Package)
Operating Temperature Option
A = Higher +125 °C Operating Temperature
Blank = Standard Product

** Only models lower than 10 volts require decimal point.

BOURNS®

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